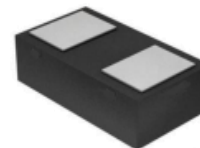


1. Features

- Capacitance: 0.25pF(typ.)
- Reverse Working Voltage: 3.3V
- IEC 61000-4-2 (ESD Air): $\pm 25\text{KV}$
IEC 61000-4-2 (ESD Contact): $\pm 20\text{KV}$
IEC 61000-4-5 (Lightning 8/20 μs): 4A

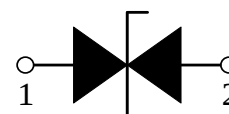
2. Pin Description



3. Applications

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA

4. Schematic Diagram



5. Order Information

Type	Package	Size (mm)	Delivery Form	Delivery Quantity
SLT211U025	DFN0603	0.60x0.30x0.30	7" T&R	15,000

6. Limiting Values($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	± 20	kV
		IEC 61000-4-2; Air Discharge	-	± 25	kV
P_{PP}	Peak Pulse Power	$t_P = 8/20\text{ }\mu\text{s}$	-	80	W
I_{PPM}	Rated Peak Pulse Current	$t_P = 8/20\text{ }\mu\text{s}$	-	4	A
T_A	Ambient Temperature Range	-	-55	125	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-	-55	150	$^\circ\text{C}$

7. Electrical Characteristics($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V_{RWM}	Reverse Working Voltage	$T_A = 25\text{ }^\circ\text{C}$	-	-	3.3	V
V_{BR}	Breakdown Voltage	$I_R = 1\text{ mA}$; $T_A = 25\text{ }^\circ\text{C}$	4.7	5.8	7.0	V
I_R	Reverse Leakage Current	$V_{\text{RWM}} = 3.3\text{ V}$; $T_A = 25\text{ }^\circ\text{C}$	-	-	0.1	μA
V_C	Clamping Voltage	$I_{\text{PP}} = 1\text{ A}$, $t_P = 8/20\text{ }\mu\text{s}$	-	9	-	V
		$I_{\text{PP}} = 4\text{ A}$, $t_P = 8/20\text{ }\mu\text{s}$	-	17	20	V
C_J	Junction Capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$	-	0.25	0.4	pF

8. Typical Characteristics

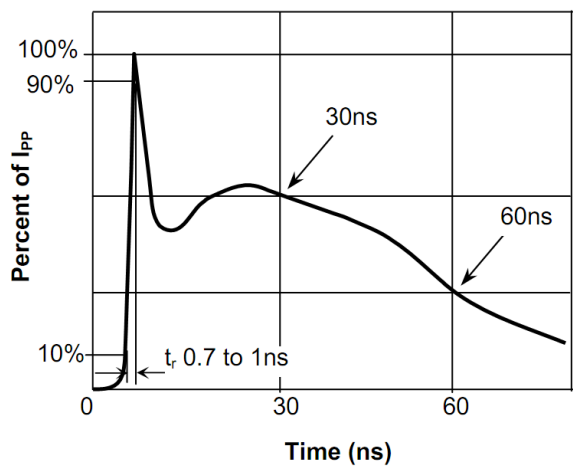


Fig.1 Pulse Waveform-ESD (IEC61000-4-2)

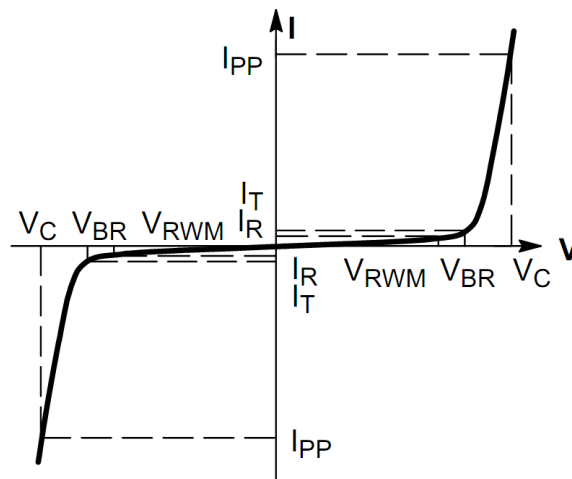


Fig.2 Bidirectional Characteristics

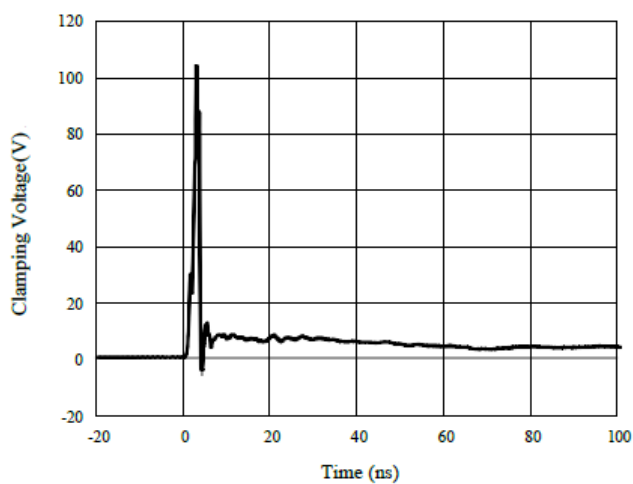


Fig.3 Clamping Voltage at IEC61000-4-2
+8kV Pulse Waveform

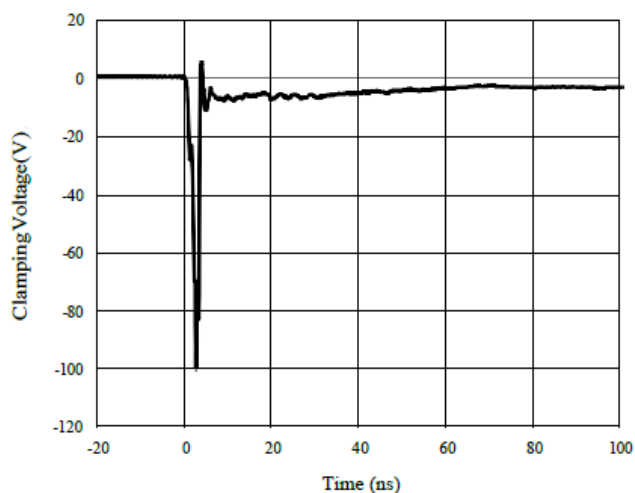
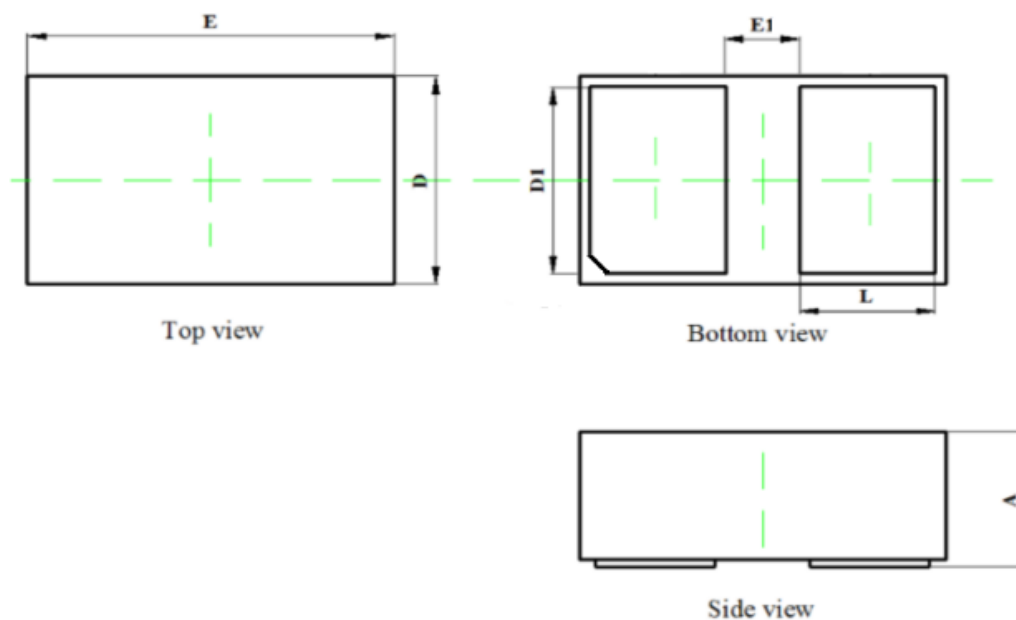


Fig.4 Clamping Voltage at IEC61000-4-2
-8kV Pulse Waveform

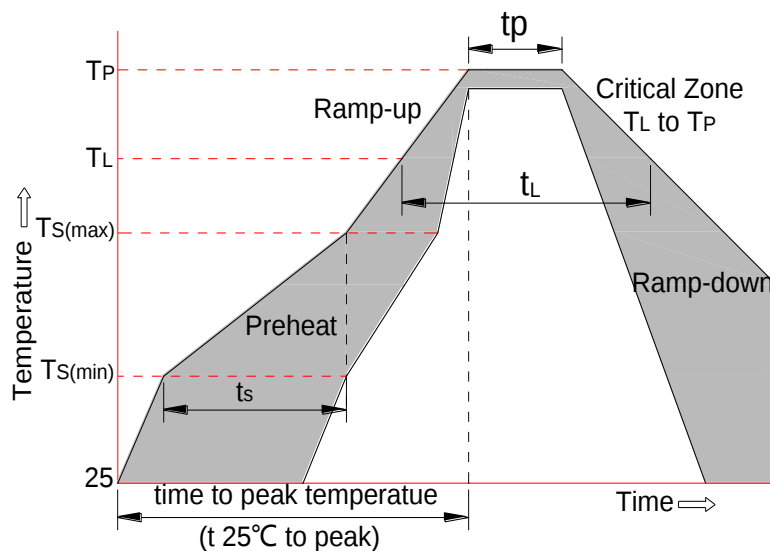
9. Package Outline Dimensions

DFN0603 Package Outline



Symbol	Dimensions In Millimeters		
	Min	Typical	Max
A	0.28	0.30	0.32
D	0.25	0.30	0.35
E	0.55	0.60	0.65
D1	0.20	0.25	0.30
E1	0.15	0.18	0.21
L	0.14	0.19	0.24

10. Soldering Parameters



Reflow Condition		Pb-Free Assembly
Pre-heat	-Temperature Min ($T_{S(min)}$)	+150°C
	-Temperature Max($T_{S(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
xTime 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C